

# 74F245

## Octal Bidirectional Transceiver with 3-STATE Outputs

### General Description

The 74F245 contains eight non-inverting bidirectional buffers with 3-STATE outputs and is intended for bus-oriented applications. Current sinking capability is 24 mA at the A Ports and 64 mA at the B Ports. The Transmit/Receive (T/R) input determines the direction of data flow through the bidirectional transceiver. Transmit (active HIGH) enables data from A Ports to B Ports; Receive (active LOW) enables data from B Ports to A Ports. The Output Enable input, when HIGH, disables both A and B Ports by placing them in a High Z condition.

### Features

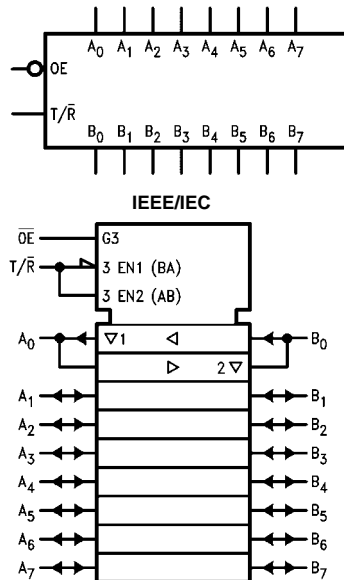
- Non-inverting buffers
- Bidirectional data path
- A outputs sink 24 mA
- B outputs sink 64 mA

### Ordering Code:

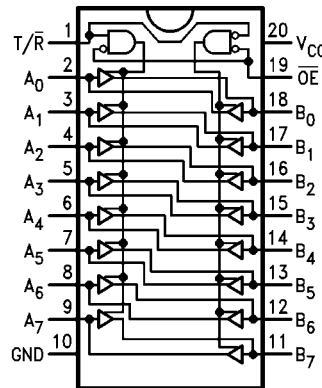
Order Number	Package Number	Package Description
74F245SC	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300 Wide
74F245SJ	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74F245MSA	MSA20	20-Lead Shrink Small Outline Package (SSOP), EIAJ TYPE II, 5.3mm Wide
74F245MTC	MTC20	20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
74F245PC	N20A	20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300 Wide

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

### Logic Symbols



### Connection Diagram



74F245 Octal Bidirectional Transceiver with 3-STATE Outputs

### Unit Loading/Fan Out

Pin Names	Description	U.L.	
		HIGH/LOW	Input $I_{IH}/I_{IL}$ Output $I_{OH}/I_{OL}$
$\overline{OE}$	Output Enable Input (Active LOW)	1.0/2.0	20 $\mu A$ /-1.2 mA
$T/\overline{R}$	Transmit/Receive Input	1.0/2.0	20 $\mu A$ /-1.2 mA
$A_0$ - $A_7$	Side A Inputs or 3-STATE Outputs	3.5/1.083 150/40(38.3)	70 $\mu A$ /-0.65 mA -3 mA/24 mA (20 mA)
$B_0$ - $B_7$	Side B Inputs or 3-STATE Outputs	3.5/1.083 600/106.6(80)	70 $\mu A$ /-0.65 mA -12 mA/64 mA (48 mA)

### Truth Table

Inputs		Output
$\overline{OE}$	$T/\overline{R}$	
L	L	Bus B Data to Bus A
L	H	Bus A Data to Bus B
H	X	High Z State

H = HIGH Voltage Level  
L = LOW Voltage Level  
X = Immaterial

**Absolute Maximum Ratings**(Note 1)

Storage Temperature	-65°C to +150°C
Ambient Temperature under Bias	-55°C to +125°C
Junction Temperature under Bias	-55°C to +150°C
V <sub>CC</sub> Pin Potential to Ground Pin	-0.5V to +7.0V
Input Voltage (Note 2)	-0.5V to +7.0V
Input Current (Note 2)	-30 mA to +5.0 mA
Voltage Applied to Output in HIGH State (with V <sub>CC</sub> = 0V)	
Standard Output	-0.5V to V <sub>CC</sub>
3-STATE Output	-0.5V to +5.5V
Current Applied to Output in LOW State (Max)	twice the rated I <sub>OL</sub> (mA)
ESD Last Passing Voltage (Min)	4000V

**Recommended Operating Conditions**

Free Air Ambient Temperature	0°C to +70°C
Supply Voltage	+4.5V to +5.5V

**Note 1:** Absolute maximum ratings are values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

**Note 2:** Either voltage limit or current limit is sufficient to protect inputs.

**DC Electrical Characteristics**

Symbol	Parameter	Min	Typ	Max	Units	V <sub>CC</sub>	Conditions	
V <sub>IH</sub>	Input HIGH Voltage	2.0			V		Recognized as a HIGH Signal	
V <sub>IL</sub>	Input LOW Voltage			0.8	V		Recognized as a LOW Signal	
V <sub>CD</sub>	Input Clamp Diode Voltage			-1.2	V	Min	I <sub>IN</sub> = -18 mA	
V <sub>OH</sub>	Output HIGH Voltage	10% V <sub>CC</sub>	2.4			V	Min	I <sub>OH</sub> = -3 mA (A <sub>n</sub> )
		10% V <sub>CC</sub>	2.0		I <sub>OH</sub> = -15 mA (B <sub>n</sub> )			
		5% V <sub>CC</sub>	2.7		I <sub>OH</sub> = -3 mA (A <sub>n</sub> )			
V <sub>OL</sub>	Output LOW Voltage	10% V <sub>CC</sub>		0.5		V	Min	I <sub>OL</sub> = 24 mA (A <sub>n</sub> )
		10% V <sub>CC</sub>		0.55				I <sub>OL</sub> = 64 mA (B <sub>n</sub> )
I <sub>IH</sub>	Input HIGH Current			5.0	μA	Max	V <sub>IN</sub> = 2.7V	
I <sub>BVI</sub>	Input HIGH Current Breakdown Test			7.0	μA	Max	V <sub>IN</sub> = 7.0V (OE, T/R)	
I <sub>BVIT</sub>	Input HIGH Current Breakdown (I/O)			0.5	mA	Max	V <sub>IN</sub> = 5.5 V (A <sub>n</sub> , B <sub>n</sub> )	
I <sub>CEX</sub>	Output HIGH Leakage Current			50	μA	Max	V <sub>OUT</sub> = V <sub>CC</sub> (A <sub>n</sub> , B <sub>n</sub> )	
V <sub>ID</sub>	Input Leakage Test	4.75			V	0.0	I <sub>ID</sub> = 1.9 μA All Other Pins Grounded	
I <sub>OD</sub>	Output Leakage Circuit Current			3.75	μA	0.0	V <sub>ID</sub> = 150 mV All Other Pins Grounded	
I <sub>IL</sub>	Input LOW Current			-1.2	mA	Max	V <sub>IN</sub> = 0.5V (T/R, OE)	
I <sub>IH</sub> + I <sub>OZH</sub>	Output Leakage Current			70	μA	Max	V <sub>OUT</sub> = 2.7V (A <sub>n</sub> , B <sub>n</sub> )	
I <sub>IL</sub> + I <sub>OZL</sub>	Output Leakage Current			-650	μA	Max	V <sub>OUT</sub> = 0.5V (A <sub>n</sub> , B <sub>n</sub> )	
I <sub>OS</sub>	Output Short-Circuit Current	-60		-150		mA	Max	V <sub>OUT</sub> = 0V (A <sub>n</sub> )
		-100		-225				V <sub>OUT</sub> = 0V (B <sub>n</sub> )
I <sub>ZZ</sub>	Bus Drainage Test			500	μA	0.0V	V <sub>OUT</sub> = 5.25V(A <sub>n</sub> , B <sub>n</sub> )	
I <sub>CCH</sub>	Power Supply Current		70	90	mA	Max	V <sub>O</sub> = HIGH	
I <sub>CCL</sub>	Power Supply Current		95	120	mA	Max	V <sub>O</sub> = LOW	
I <sub>CCZ</sub>	Power Supply Current		85	110	mA	Max	V <sub>O</sub> = HIGH Z	

## AC Electrical Characteristics

Symbol	Parameter	$T_A = +25^\circ\text{C}$ $V_{CC} = +5.0\text{V}$ $C_L = 50\text{ pF}$			$T_A = -55^\circ\text{C to } +125^\circ\text{C}$ $C_L = 50\text{ pF}$		$T_A = 0^\circ\text{C to } +70^\circ\text{C}$ $C_L = 50\text{ pF}$		Units
		Min	Typ	Max	Min	Max	Min	Max	
$t_{PLH}$	Propagation Delay	2.5	4.2	6.0	2.0	7.5	2.0	7.0	ns
$t_{PHL}$	$A_n$ to $B_n$ or $B_n$ to $A_n$	2.5	4.2	6.0	2.0	7.5	2.0	7.0	
$t_{PZH}$	Output Enable Time	3.0	5.3	7.0	2.5	9.0	2.5	8.0	ns
$t_{PZL}$		3.5	6.0	8.0	3.0	10.0	3.0	9.0	
$t_{PHZ}$	Output Disable Time	2.0	5.0	6.5	2.0	9.0	2.0	7.5	
$t_{PLZ}$		2.0	5.0	6.5	2.0	10.0	2.0	7.5	

**Physical Dimensions** inches (millimeters) unless otherwise noted

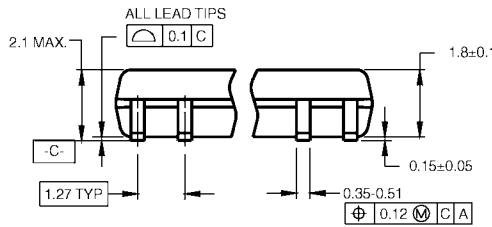


**20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300 Wide  
Package Number M20B**

**Physical Dimensions** inches (millimeters) unless otherwise noted (Continued)



LAND PATTERN RECOMMENDATION



DIMENSIONS ARE IN MILLIMETERS



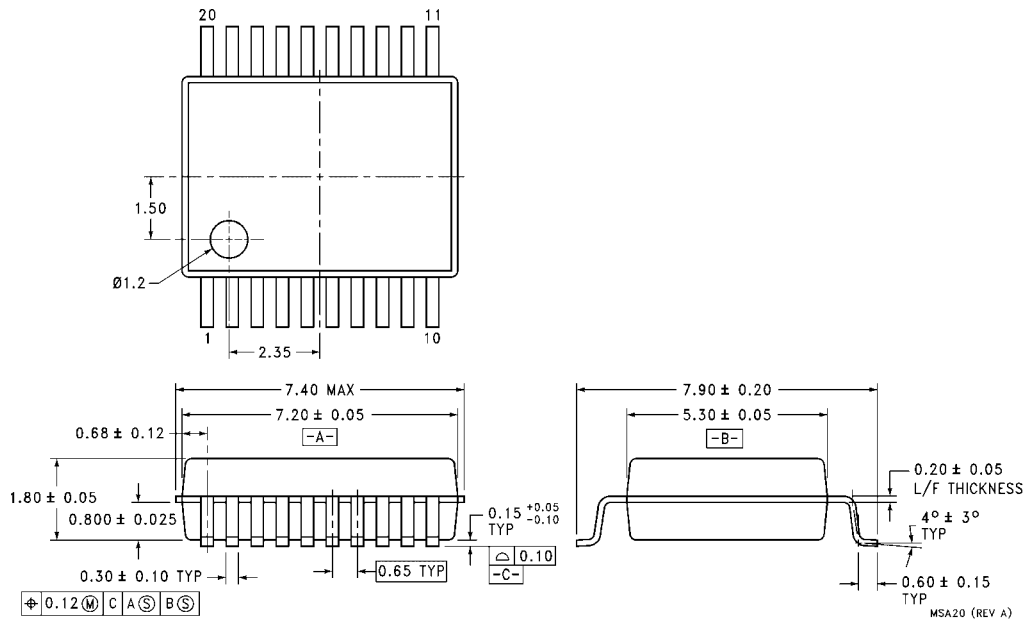
DETAIL A

- NOTES:
- A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.
  - B. DIMENSIONS ARE IN MILLIMETERS.
  - C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

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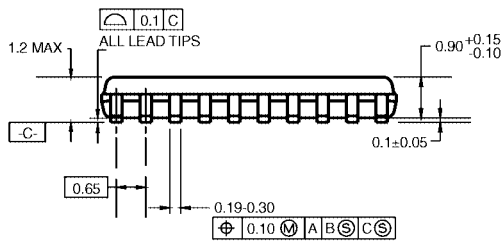
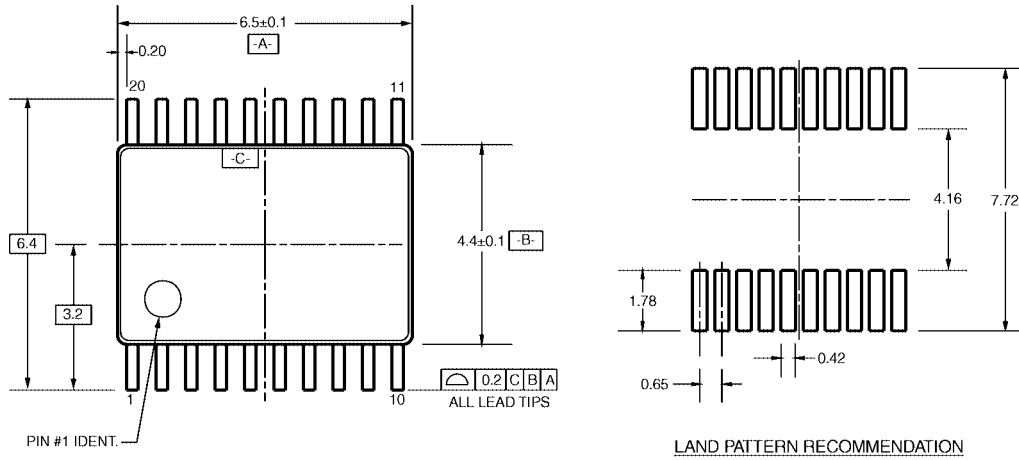
**20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide Package Number M20D**

**Physical Dimensions** inches (millimeters) unless otherwise noted (Continued)



**20-Lead Shrink Small Outline Package (SSOP), EIAJ TYPE II, 5.3mm Wide  
Package Number MSA20**

**Physical Dimensions** inches (millimeters) unless otherwise noted (Continued)

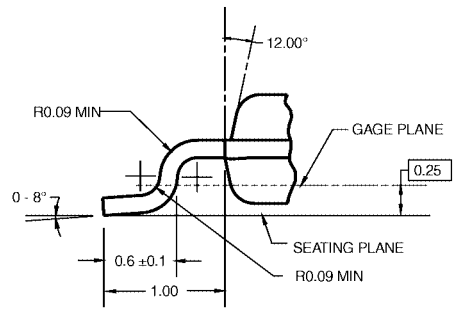
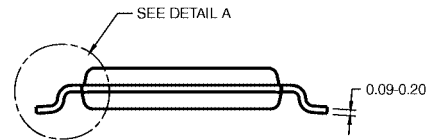


DIMENSIONS ARE IN MILLIMETERS

NOTES:

- A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AC, REF NOTE 6, DATE 7/93.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.

MTC20RevD1

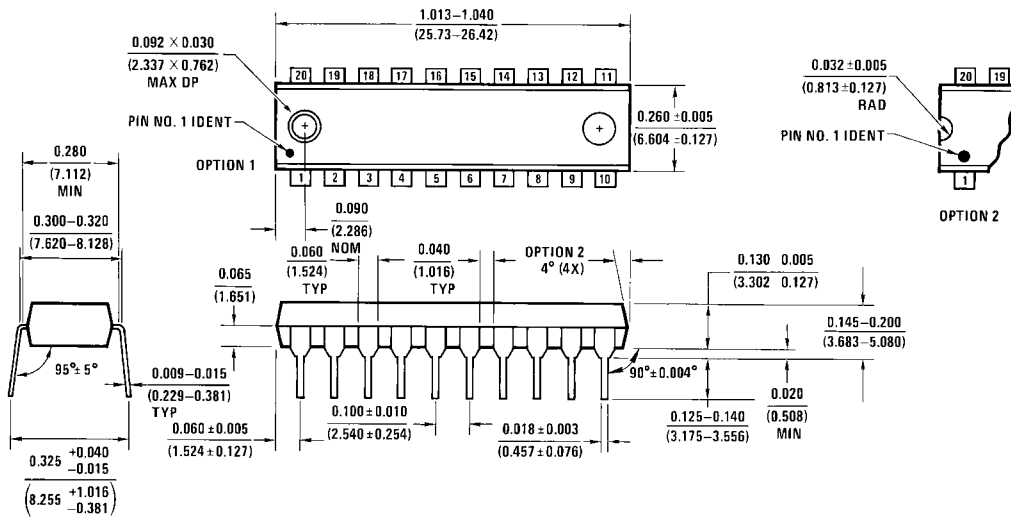


DETAIL A

**20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide  
Package Number MTC20**



**Physical Dimensions** inches (millimeters) unless otherwise noted (Continued)



**20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300 Wide  
Package Number N20A**

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